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Nagoya, JAPAN

Additional name(s) & address(es) attached? ☐ Yes ☒ No

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PATENT
REEL: 014792 FRAME: 0719

L-680-682

938-0107

ASSIGNMENT

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar(\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by DAIDO METAL COMPANY LTD., a corporation organized under the laws of Japan, located at 13F, Nagoya Hirokoji Bldg., 3-1, Sakae 2-chome, Naka-ku, Nagoya, Japan, receipt of which is hereby acknowledged I do hereby sell and assign to said DAIDO METAL COMPANY LTD., its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

MULTI-LAYERED ALUMINUM-BASE BEARING

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith,

and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said DAIDO METAL COMPANY LTD., its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted, as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said DAIDO METAL COMPANY LTD.

Signed on the date(s) indicated aside signatures:

	INVENTOR(S) (発明者フルネームサイン)	Date Signed (署名日)	WITNESSES (立会人サイン)
1)	<u>Yukihiko KAGOHARA</u> Yukihiko KAGOHARA	<u>August 1, 2003</u>	<u>Kujabide Hensho</u>
2)	<u>Takeshi HOSHINA</u> Takeshi HOSHINA	<u>August 1, 2003</u>	<u>Katsumi Sawano</u>
3)	<u>Hideo ISHIKAWA</u> Hideo ISHIKAWA	<u>August 1, 2003</u>	<u>Hirofuku Kayahara</u>
4)	<u>Masaaki SAKAMOTO</u> Masaaki SAKAMOTO	<u>August 1, 2003</u>	<u>Tadatoshi Nagasaki</u>
5)	_____	_____	_____
6)	_____	_____	_____
7)	_____	_____	_____
8)	_____	_____	_____
9)	_____	_____	_____